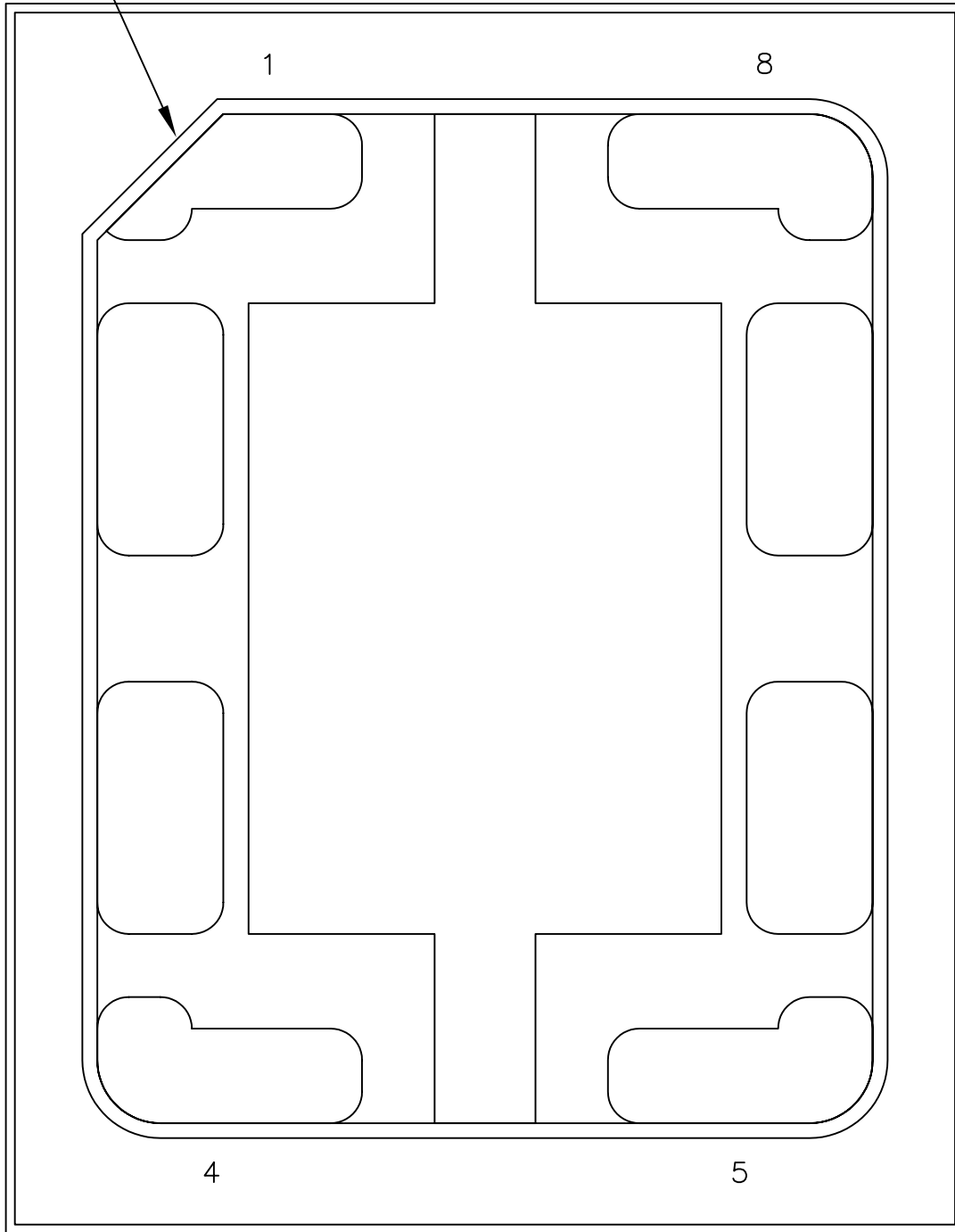


PIN #1 IDENTIFIER



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006						
CUSTOMER:			DIE SIZE:					8 Lead 150 mils SOIC Open-Pak Bonding Diagram		
WIRE TYPE/ SIZE:			NO. OF WIRES:							
THIRD ANGLE PROJECTION	REVISIONS			SIZE		PART NO.	REV			
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES. DO NOT SCALE DRAWING	ECN NO.	DATE	DESCRIPTION		APPROVED		SOIC150-08-OP-01	2		
	10506	11/1/05	PRODUCTION RELEASE		D.BENANDO					
DRAWN BY	W. GRIFFITTS	DATE	10/28/05	PACKAGE SIZE:	0.195" x 0.152"	SCALE	30X	SHEET		
APP BY	P. FLASKERUD	DATE	10/28/05	DIE PAD SIZE:	0.100" x 0.075"	CAD FILE	SOIC150-08-OP-01-R2.DWG	1 OF 1		